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Building environment design — Embedded radiant heating and cooling systems —

Part 3: Design and dimensioning

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AMENDMENT 1

ISO 11855-3:2021/Amd

Conception de l'environnement des bâtiments — Systèmes <u>intégrés</u> de chauffage et de refroidissement par rayonnement <u>intégrés — —</u>

Partie 3: Conception et dimensionnement

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ii

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Building environment design — Embedded radiant heating and cooling systems —

Part 3:

Design and dimensioning

Normative references

Delete the publication date from the following entries:

ISO 11855-2, Building environment design — Embedded radiant heating and cooling systems — Part 2 Determination of the design heating and cooling capacity

ISO 11855 5, Building environment design—Embedded radiant heating and cooling systems—Part S Installation

AMENDMENT 1

5.1.4

Modify to the following:

The field of characteristic curves of a floor heating system with a specific pipe spacing W shall at least contain the characteristic curves for values of the thermal resistance of surface covering $R_{\lambda\rm B}=0$, $R_{\lambda\rm B}=0,05$, $R_{\lambda\rm B}=0,10$ and $R_{\lambda\rm B}=0,15$ (m²K/W), in accordance with ISO 11855-2 (see Figure 1). In order to apply values of $R_{\lambda\rm B}>0,15$ (m²K/W), it is possible only when the values are verified.

5.1.5 Figure 1

Modify to the following:

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